

# Chips JU calls 2026 and early insights into 2027

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**National Contact Point** (NCP) for the Horizon Europe-programme as well as Chips JU – counselling on opportunities, requirements and rules for applying

Representing Denmark in **Programme Committees** under Horizon Europe and **Chips JU's Public Authorities Board** - dialogue with Commission and Member States about structure and content of work programmes



# The Chips Joint Undertaking (Chips JU)

## Members of the Chips JU-partnership




- The European Commission
- Participating States
  - Austria, Belgium, Bulgaria, Croatia, Cyprus, Czechia, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Israel, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Türkiye, United Kingdom
- Private Members/Industry Associations:
  - AENEAS, EPoSS, INSIDE

**Goal:** catalysing research, development, and manufacturing capabilities across Europe; accelerate innovation and sustainable growth in key industries by strengthening Europe's competitiveness in semiconductors through collaboration, resilient supply chains, and advanced technologies.

# Chips Joint Undertaking: ECS and C4EI

## Appendix 7 2026: Electronic Components and Systems (ECS)

- Collaborative actions; Both bottom-up and top-down/focus topics
- 10 calls in 2026 with a budget of 179 million EUR

	National co-funding is available (IFD-call)
	No national co-funding required (own contribution may be necessary)
	Participation not possible

Topic-ID	Topic	Indic. budget (exp. projects)	Deadline
HORIZON-JU-Chips-2026-1-IA	Global call 2026 (IA)	40 M€ (2-3)	07 May PO, 17 Sep FPP
HORIZON-JU-Chips-2026-FT1-IA	Resilience on Power Electronics (IA)	20 M€ (2)	16 Sep
HORIZON-JU-Chips-2026-FT2-IA	Resilience on Photonics (IA)	20 M€ (2)	16 Sep
HORIZON-JU-Chips-2026-FT3-IA	Resilience on Health (IA)	20 M€ (1)	16 Sep
<b>HORIZON-JU-Chips-2026-IA-FT4</b>	<b>AI-assisted Methods and Tools for Software-Defined Vehicle Engineering Automation (IA)</b>	<b>20 M€ (1)</b>	<b>03 Mar</b>
HORIZON-JU-Chips-2026-1-RIA	Global call 2026 (RIA)	50 M€ (4)	07 May PO, 17 Sep FPP
HORIZON-JU-Chips-2026-2-RIA	Resilience on 6G radio communication systems (RIA)	20 M€ (1)	16 Sep
HORIZON-JU-Chips-2026-3-RIA	Joint call with Digital Partnership and TTC countries (RIA)	5 M€ (2)	16 Sep
HORIZON-JU-Chips-2026-CSA	Supply chain resilience (CSA)	2 M€ (1)	22 Sep
HORIZON-JU-Chips-2026-SDV-CSA	Preparing a European autonomous driving stack ecosystem building on next-generation SDV software and hardware computing architectures (CSA)	2 M€ (1)	22 Sep

# Chips Joint Undertaking: ECS and C4EI

## Appendix 8 2026: Chips for Europe Initiative (C4EI)

- Covers pilot lines, design platform, competence centres, quantum chips technology and activities around skills
- 8 calls in 2026 with a budget of 215 million EUR



National co-funding is available (IFD-call)



No national co-funding required (own contribution may be necessary)



Participation not possible

Topic-ID	Topic	Indic. budget (exp. projects)	Deadline
DIGITAL-JU-CHIPS-2026-DET-CSA	Design Enablement Teams (DET) related to the Chips Design platform (CSA)	5 M€ (10)	24 Sep
DIGITAL-JU-CHIPS-2026-AIDP-GfP	AI chips and systems for EU compute infrastructure; strengthening Europe's AI development (Grant for Procurement)	100 M€ (1)	24 Sep
DIGITAL-JU-CHIPS-2026-SKILLS-HoE-SG	Development of Skills Hubs of Excellence in Europe (Simple Grant)	20 M€ (5)	24 Sep
DIGITAL-JU-CHIPS-2026-SKILLS-PF-SG	Pilot Federation to network existing European Vocation Education and Training providers; Skills Development (Simple Grant)	10 M€ (1)	24 Sep
DIGITAL-JU-CHIPS-2026-SKILLS-SCD-CSA	Chip Design Skills Programme aimed at inspiring new generations to pursue careers in the semiconductor sector; Skills development (CSA)	15 M€ (1)	24 Sep
HORIZON-JU-CHIPS-2026-QUANTUM-1-RIA	Quantum Chips Design (RIA)	30 M€ (1)	23 Sep
HORIZON-JU-CHIPS-2026-QUANTUM-2-RIA	Enabling technologies for Quantum Chips (RIA)	20 M€ (3-4)	24 Sep
DIGITAL-JU-Chips-2026-SG-JAPAN	<i>Joint action between the EU and Japan on semiconductors (to be confirmed)</i>	15 M€ (3)	24 Sep

# Looking ahead to 2027 and beyond

## Potential focus areas for WP2027: ECS and C4EI

- Prosperity: competitive European semiconductor ecosystem; enhancing Europe's value creation across end-markets
- Indispensability: maintain and develop Europe's leadership; secure critical control points in the global semiconductor value chain
- Resilience: stable and reliable supply of trustworthy semiconductors for Europe's most critical sectors
  - Balance between bottom-up and focus topics
- C4EI: More strategic and future oriented

## The Chips JU annexes/work programmes 2027 are last of the Multiannual Work Programme 2023-2027

- New Chips Act 2.0 on the way
- New MFF-period from 2028-2034

# Open consultation: Preparation of ECS SRIA 2027

The industry associations (AENEAS, EPoSS, and INSIDE) have started preparations for the Electronic Components and Systems Strategic Research and Innovation Agenda (ECS-SRIA 2027)

SRIA sets out Europe's medium and long-term research and innovation priorities for ECS; reference document for calls

Deadline: May 10<sup>th</sup>

Link for more information: [Open consultation to prepare the ECS SRIA 2027](#)

# Contact information

## **EuroCenter**

*National Contact point*

Guidance, practical information and assistance on all aspects of participation in Horizon Europe and Chips JU

## **Innovation Fund Denmark**

*National Funding Authority*

Guidance on national co-financing



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